

SOT776-1

plastic thermal enhanced shrink small outline package; no leads; 14 terminals; body 12 x 12 x 2.1 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSSON14
Package type industry code	HSSON14
Package style descriptive code	HSSON (thermal enhanced shrink small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-6-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	2.1	2.2	mm
A ₂	package height	[tbd]	-	2.1	[tbd]	mm
n ₂	actual quantity of termination	-	-	14	-	

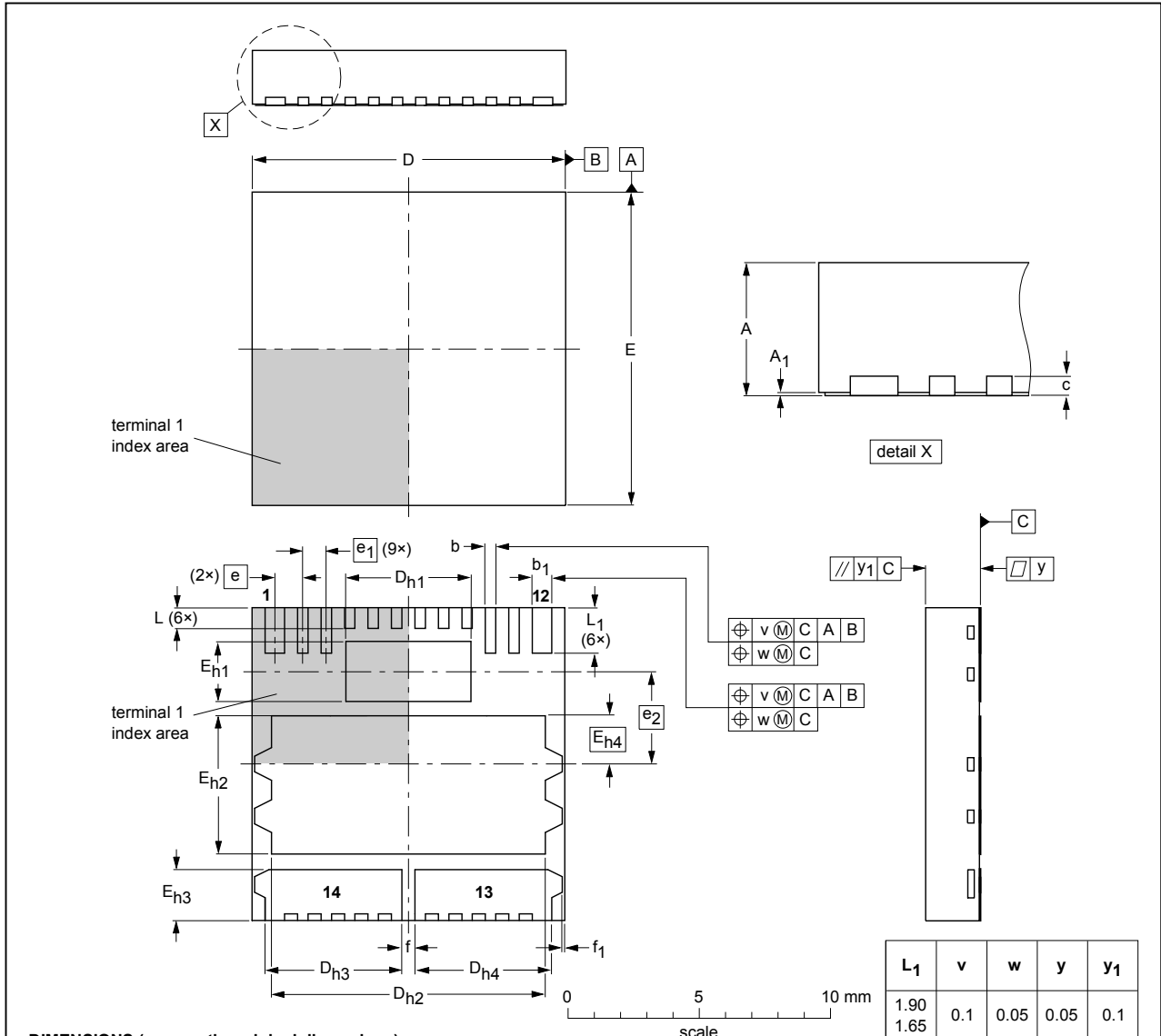


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2. Package outline

HSSON14: plastic thermal enhanced shrink small outline package; no leads; 14 terminals; body 12 x 12 x 2.1 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾ _{max}	A ₁	b	b ₁	c	D ⁽¹⁾	D _{h1}	D _{h2}	D _{h3}	D _{h4}	E ⁽¹⁾	E _{h1}	E _{h2}	E _{h3}	E _{h4}	e	e ₁	e ₂	f	f ₁	L
mm	2.2	0.05 0.00	0.47 0.33	0.82 0.68	0.5	12.1 11.9	4.95 4.65	10.65 10.35	5.4 5.1	5.4 5.1	12.1 11.9	2.45 2.15	5.45 5.15	2.1 1.8	1.85	1.075	0.9	3.55	0.6 0.4	0.15 0.05	0.95 0.70

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT776-1	---	---	---		03-11-28 05-06-06

Fig. 1. Package outline HSSON14 (SOT776-1)

plastic thermal enhanced shrink small outline package; no leads; 14 terminals; body 12 x 12 x 2.1 mm

3. Soldering

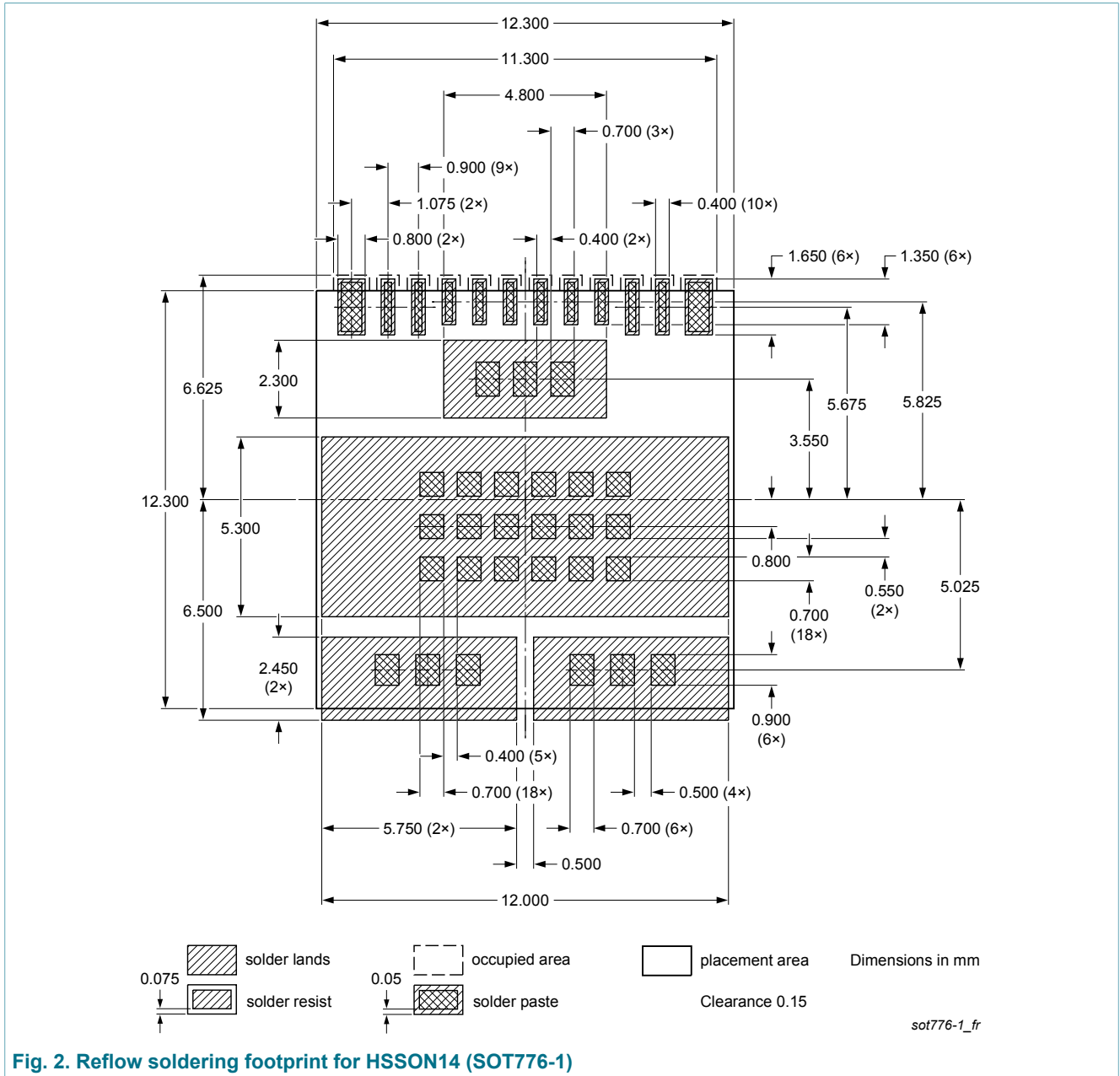


Fig. 2. Reflow soldering footprint for HSSON14 (SOT776-1)

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4. Legal information

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